

ABSTRACT

A polishing liquid containing abrasive grains containing cerium oxide and an ammonium salt, in which a pH is 9.00 or more. A polishing method including polishing a member to be polished containing copper by using the above-described polishing liquid. A method for manufacturing a component, including obtaining a component by using a polished member polished by the above-described polishing method. A method for manufacturing a semiconductor component, including obtaining a semiconductor component by using a polished member polished by the above-described polishing method.